In the claims:

Claims 1 to 20 (canceled).

Claim 21 (currently amended) A process of providing a high density module produced by a process comprising the steps of:

providing a circuit board having a substantially planar top surface for connection to at least one integrated circuit package;

providing an integrated circuit package having a pair of opposing major surfaces and at least one edge surface disposed between said opposing major surfaces, one of said at least one edge surface having at least one electrical terminal disposed thereon; and

electrically connecting said at least one electrical terminal on said at least one edge surface of said integrated circuit package ~~having a major surface and side minor surfaces extending from said major surface, at least one of said side surfaces having electrical side surface terminals thereon in intimate contact with and electrically connected~~ to said ~~printed circuit board at said~~ top surface of said printed circuit board..

Claim 22 (currently amended) The process as recited in claim 21 further including the step of electrically and perpendicularly connecting at least two said integrated circuit packages to said circuit board at a said edge .

Claim 23 (previously presented) The process as recited in claim 21 further including the step of disposing a solder ball between said side surface terminal of said integrated circuit package and said top of said circuit board.

Claim 24 (previously presented) The process as recited in claim 21 further including the step of disposing solder columns between said integrated circuit and said top of said circuit board.

Claim 25 (previously presented) The process as recited in claim 21 further including the step of integrally attaching at least three tabs to said circuit board.

Claim 26 (previously presented) The process as recited in claim 21 wherein said integrated circuit package is further defined as being connected in a substantially perpendicular manner to said circuit board.

Claim 27 (previously presented) The process as recited in claim 21 wherein said integrated circuit package is further defined as being connected at an angle between 30 and 90 degrees to said circuit board.

28 (new) The process as recited in claim 21 wherein said at least one edge surface is four edge surfaces, each of said four edge surfaces disposed between said major surfaces to form a closed package with said major surfaces.